**Minutes of the technical board meeting, February 13, 2014**

Topic: Assembly of the next EMCMs and PXD6

Present: Carlos Marinas, Carsten Niebuhr, Christian Kiesling, Christian Koffmane, Christian Kreidl, Hans Krüger, Laci Andricek, Manfred Valentan, Rainer Richter, Hans-Günther Moser

1. Status of the existing EMCMs. Four have been assembled so far, all of them have defects. Mostly the switchers have problems. Some tests can still be performed (test of the DHP-DHH link with P4-1) and should be done before new EMCMs become available
2. Availability of components:

Switcher:

|  |  |  |
| --- | --- | --- |
| Version | Untested, no bumps | Bumped and tested |
| B18V1 | 45 | 72 |
| B18V2 (for gating) | 112 | 13 + 4\* |

\*at HLL

DCD

|  |  |  |
| --- | --- | --- |
| Version | Untested | Tested |
| V2(3) | 330 | 0 |
| V4 | 200 | 0 |
| pipeV1 | 200 | 0 |

 Christian will prepare 8 V2 DCDs next week

 DHP

|  |  |  |
| --- | --- | --- |
| Version | Untested | Tested |
| DHP0.2 | 5\* | 3 |
| DHPT10 | 100 |  |

 \*these are reworked ones, not all may be ok

 Tested DHPT1.0 will become available in some weeks

 EMCM2: 8 will be cut, available end of next week

 EMCM3: ? to be finished within the next 4-6 weeks

 PXD6: one long matrix

1. Program

EMCM2:

In order to test whether the switchers work properly in a row two EMCM2 will be populated (in 2 weeks):

Each: 1 DCDV2, 1 DHP0.2, 6 Switcher B18V1

PXD6: The remaining PXD6 matrix will be populated in parallel with 2 DCDV2, 2 DHP0.2, 4 Switcher B18V2. The position which needs bump removal will not be equipped. This matrix will be used to test the gated mode (Switcher control by DHH).

EMCM3 will be populated with the final chips SwitcherB18V2, DHPT1.0 and DCDpipeV1 (fully) as soon as they become available (ca 2 Months). At least one should be equipped with a long 50cm Kapton (already available from Taiyo). The final tests should be based on these modules:

* High speed link
* Full speed operation with acceptable noise
* Gated mode

The components need to be prepared and tested in the next week.

1. AOB

For tests of DHPT a wire bond adapter should be prepared ant HLL and sent to Bonn

Valencia needs EMCMs for testing their needle cards